



Surface Preparation and Cleaning Conference 2024

Call for Papers

SPCC Call for Papers and Presentations

Abstract Submissions Due **December 29th, 2023**

Abstracts in (MS Word or PDF only) should be two-page (maximum) and include the selected topic. Authors are also invited to expand their papers for submission to a special peer-reviewed edition of Microelectronics Engineering to be published after the conference. Only full papers submitted by June 1, 2024 will be considered for publication. When submitting an abstract, please indicate if you also plan to submit a full paper for this publication.

SPCC Call for Papers and Publications

The SPCC conference focuses on addressing the current and future challenges that the surface preparation and cleaning industry is facing. The presentations specifically target the latest research on cleaning technologies for the electronics industry. These presentations will cover a wide range of topics, including front-end, back-end, packaging, equipment, materials, and metrology developments, as well as issues related to wafer cleaning.

We strongly encourage global semiconductor manufacturers, suppliers, researchers, and students to submit abstracts on various aspects of advanced cleaning and surface preparation. This includes, but is not limited to, the following topics: wet processes, surface preparation, new experimental work and findings, and subject area reviews.

- Cleaning challenges associated with advanced memory technologies, including pattern collapse, selective etching, particle removal and surface preparation in DRAM, 3D-NAND, and emerging memories.
- Challenges associated with wet and dry cleaning, surface preparation, and controlled removal of materials associated with advanced logic/memory structures - including FinFET, nanosheets and both horizontal and vertical nanowire devices.
- New surface preparation approaches to enable More-than-Moore process scaling.
- Defect/particle reduction techniques for advanced CMOS or automotive devices.
- Improvement in environmental, safety, health, and sustainability performance.
- Surface preparation and clean challenges associated with Ge, III-V, GaN, SiC and 2D systems.
- Multi-metal post etch cleans challenges in FEOL, BEOL and emerging memory.
- Post CMP cleaning challenges.
- Metal and low- κ dielectric related cleaning and ashing issues for 3D and advanced interconnect.
- Unique challenges associated with advanced, optical, and EUV mask cleaning, including surface preparation and treatment for resist adhesion enhancement.
- Control of contamination during cleaning, fabrication, exposure, storage, and transport of substrates and masks.
- Challenges associated with providing high purity water and chemicals and the associated delivery systems.
- Analytical techniques relevant to surface preparation.
- In-situ monitoring techniques and statistical process control of cleaning or wet processes.
- Advances in trace particle and metal detection metrology on wafer and in-situ.
- The effect of surface preparation on electrical/device performance.
- Influence of back-end processes and contaminants on packaging performance & reliability
- Surface preparation and passivation challenges in photovoltaic, MEMS, and nanoelectronics.

Abstracts in (MS Word or PDF only) should be two-page (maximum) and include the selected topic and relevant data. Authors are also invited to expand their papers for submission to a special peer reviewed edition of the Microelectronics Engineering to be published after the conference. Only full papers submitted by June 1, 2024 will be considered for publication. When submitting an abstract, please indicate if you also plan to submit a full paper for this publication.

Submit abstracts by email to dmaloney@linx-consulting.com by December 29th, 2023.

Final presentations will be due on March 25, 2024.

For more information please contact Mark Thirsk at mthirsk@linx-consulting.com, or Audrey Parton at aparton@linx-consulting.com.

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Business Interface Conference

The Business Interface Conference 2024 will be hosted with the SPCC. The Business Interface Conference is designed to complement the SPCC and will provide critical insights on the semiconductor industry outlook and evolving industry dynamics as well as review key trends in advanced wet processes, systems, and technologies.

Save the Dates!

Tuesday, April 24, 2024

Business Interface Conference

9:00 am - 4:30 pm

Informal Networking Reception

5:30 pm – 8:00 pm

Wednesday, April 25, 2024

SPCC Conference - Day 1

9:00 am - 4:30 pm

SPCC Poster Session & Networking Reception

6:00 pm - 8:00 pm

Thursday, April 26, 2024

SPCC Conference - Day 2

9:00 am - 4:30 pm

Location:

Wild Horse Pass Resort - Gila River Resorts & Casinos

5040 Wild Horse Pass Blvd

Chandler

Arizona 85226

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